

SOLID STATE RELAY (I/O Module) MAXIMUM LOAD CURRENT 1 A SN SERIES

RoHS compliant

FEATURES

- I/O modules for interface between CPU and external input devices or loads
- Ultra slim and light weight, SIL terminals type I/O modules for high density mounting
 - —Size: 5 (W) \times 20 (L) \times 17 (H) mm
 - -Weight: approximately 3.0 to 3.5 g
- High isolation by employing photo-coupled devices (between input and output: 2,500 V rms)
- Long life and maintenance free
- All solid state I/O module
- Compatible with NY relay size and terminals arrangement (only output module type)
- RoHS compliant since date code: 6703 (except 204-207) Please see page 9 for more information



ORDERING INFORMATION

• Input module

SN - A 100 BF

(b) (c) [Example]

(a)	Series Name	SN : SN Series
(b)	Input Voltage	A: AC type D: DC type
(c)	Nominal Voltage	100 BF: 100 VAC 200 BF: 200 VAC 12/24 B: 12/24 VDC

Output module

(a)	Series Name	SN: SN Series		
(b)	Nominal Voltage (Input side)	3: 3 VDC (only AC type) 5: 5 VDC 12: 12 VDC 24: 24 VDC		
(c)	Load Voltage	A: AC type D: DC type		
(d)	Load Current	01 : 1 A		
(e)	Kinds of Inverse Connection Protecting Element	AC type Nil : with varistor NV: without varistor DC type Nil : Diode HZ: Zener diode		
(f)	Zero Cross function (AC type)	F : without zero cross function C : with zero cross function		
(g)	Output Polarity (DC type)	Nil : Standard polarity R : Reverse polarity		
(h)	Switching Speed (DC type)	Nil : Standard T : High speed type		

■ SPECIFICATIONS

• INPUT MODULE (SN-() B Type)

Item		AC Input Module		DC Input module		
		100 VAC type	200 VAC type	12/24 VDC type		
INPUT Input voltage range 80 to 132 Vrms			160to 265 Vrms	9.6 to 28.8 VDC		
	Rating input current	Approximately 7 mArms		Approx. 5 mA at 12 VDC	Approx. 10 mA at 24 VDC	
	Power frequency range	47 to 63 Hz		-	-	
	Must operate voltage (max.)	80 Vrms	160 Vrms	9.6 VDC	VDC	
	Must release voltage (max.)	30 Vrms	60 Vrms	5.0 VDC		
	Must release current (max.)	2 mArms		1.5 mA		
OUTPUT	DC supply voltage (VDD)	4 to 6 VDC				
side	Max. output current (VDD=5V)	±4 mA		±0.4 mA		
	Output logic	Operate with negative true logic (active flow)				
Maximum o	operate time (max.)	25 ms		10ms		
Maximum ı	release time (max.)	30 ms		10ms		
Insulation r	resistance (initial value)	Minimum 1,000 M Ω (at 500VDC) (for input-output)				
Dielectric s	trength	2,500 Vrms 1 minute (for input-output)				
Operating	temperature range (no frost)	-30°C to +85°C				
Storage ter	mperature range (no frost)	-40°C to +100°C				
Case color		Yellow		White		
Weight		Approximately 2.0 g		Approximately 3.3 g		

• OUTPUT MODULE Standard Type

Item Remarks			AC Out with zero cross	out module without zero cross	DC Output module	
INPUT side	Nominal Voltage (DC)		3 V, 5 V, 12 V, 24 V		5 V, 12 V, 24 V	
Side	Operate Voltage Range		±20% of nominal voltage			
	Must Operate Voltage		max.80% of nominal voltage			
	Must Release Voltage		Minimum 1 VDC (minimum 0.5 \		m 0.5 V*)	*3 VDC type
		3 VDC Type	130 Ω	180 Ω	_	
	lancet lance de acc	5 VDC Type	330 Ω	470 Ω	390 Ω	
	Input Impedance (±10%)	12 VDC Type	1,0k Ω	1,5k Ω	1,2k Ω	
		24 VDC Type	2,2k Ω	3,0k Ω	2.4k Ω	
OUTPUT	Load Voltage Range		24 to 265 Vrms		3 to 30 VDC	
side	Maximum Load Current		1.0 Arms		1.0 A	see CHARACTERISTIC DATA
	Minimum Load Current		10 mArms		1 mA	
	Switching Current		50 A (60 Hz)		3 A (10 ms)	
Max. Off-State	Leakage Current		1.5 mArms (at 100 Vrms 60 Hz) 3.0 mArms (at 200 Vrms 60 Hz)		0.1 mA (at 30 VDC)	
	Max. On-State Voltage Drop		1.2 Vrms		1.2 V	at max. load current
Maximum Op	perate Time (max.)		1 ms	1/2 cycle ±1 ms	1 ms	
Maximum Release Time			1/2 cycle + 1ms		1 ms	
Insulation Resistance			Minimum 1,000 M Ω (at 500 VDC)			for input putput
Dielectric Strength			2,500 Vrms 1 minute			for input-output
Operating Temperature Range			-30°C to + 85°C			no
Storage Tem	torage Temperature Range			+100°C		frost
Case Color			Black		Red	
Weight			Approxima	ately 3.5 g	Approximately 2.9 g	

3

• OUTPUT MODULE High Speed Switching Type

Item			AC Output module	Remarks
INPUT side	Nominal Voltage (DC)		5 V, 12 V, 24 V	
side	Operate Voltage Range		±20% of nominal voltage	
	Must Operate Voltage Must Release Voltage		80% of nominal voltage	
			Minimum 1 V	
		5 VDC Type	330 Ω ±10%	
	Input Impedance	12 VDC Type	1,0 k Ω ±10%	
		24 VDC Type	2,0 k Ω ±10%	
OUTPUT	Load Voltage		DC3 to 30V	
side	Maximum Load Current		1.0 A	see CHARACTERISTIC DATA
	Minimum Load Current		1 mA	
	Switching Current		3 A (10 ms)	
	Max. Off-State Leakage Current		0.1 mA (at 30 VDC)	
	Max. On-State Voltage Drop		1.2 V	at max. load current
Maximum Operate Time			max. 5 µs	at DC 5 V 0.1A
Maximum Release Time			max. 25 µs	
Insulation Resistance			Minimum 1,000 M Ω (at 500 VDC)	5
Dielectric Strength			2,500 V rms 1 minute	for input-output
Operating Temperature Range			-40°C to + 100°C	
Storage Temperature Range			-30°C to + 85°C	
Case Color			Red	
Weight			Approximately 2.9 g	

■ BLOCK DIAGRAM

• INPUT MODULE

LOAD		INSULATION CIRCUITS	Input/Output waveform (resistive load)	
DC Logic	Photo-transistor coupler	terminal 2(~) • Circuit • 4 001 terminal • 5 GND	Input signal OFF Output signal "H" "L"	
output	Photo-transistor coupler	1 (+/-) Input Input Circuit 2 (+/-) Buffer Circuit	Input signal ON OFF Output signal "H" L"	

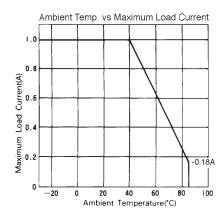
• OUTPUT MODULE

LOAD		INSULATIONCIRCUITS	Input/Output waveform (resistive load)
AC	Photo-triac coupler	3+ O Photo-triac coupler O Coutput terminal circuit	Source voltage of load Input signal OFF Load current
DC	Photo-transistor coupler	Input Input circuit terminal 4- o Photo-transistor coupler terminal terminal 4- o Photo-transistor coupler terminal terminal terminal 4- o Photo-transistor coupler terminal t	Input signal OFF Load current

^{*} AC type without varistor / DC type with zenor diode available.

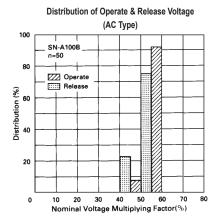
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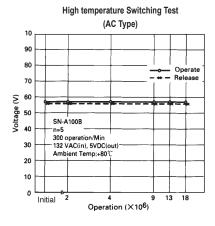
• OUTPUT MODULE

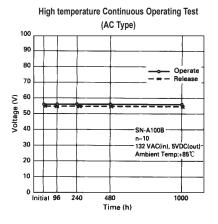


■ REFERENCE DATA

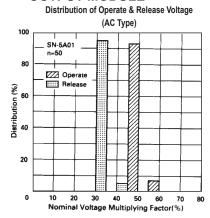
• INPUT MODULE

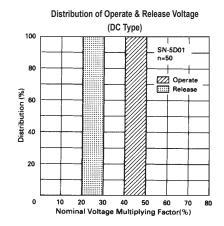


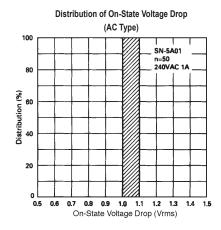




• OUTPUT MODULE



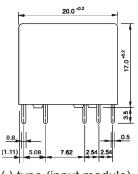




■ DIMENSIONS

Dimensions

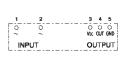
SN-A () type (input module)

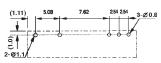


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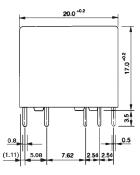
Schematics (BOTTOM VIEW)

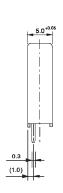






SN-D () type (input module)

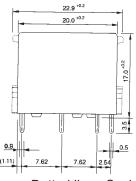


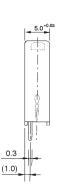


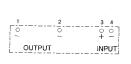
1 2 3 4 5 ○ ○ ○ ○ ○ ○ +/- +/- № ОЛГ ОНО INPUT OUTPUT

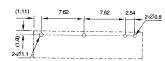


SN-A () type (output module)



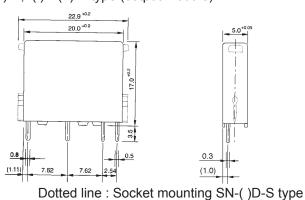


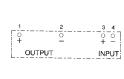


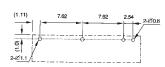


Dotted line: Socket mounting SN-()A-S type

SN-() D, ()D () R type (output module)



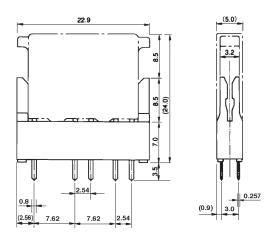




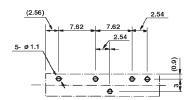
* Reverse polarity type available

reverse polarity type available

Socket Dimensions



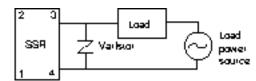
Socket PC board mounting hole layout



Unit: mm

■ NOTES

- 1. Polarity of terminals is pre-determined. Please design your circuit accordingly.
- 2. Socket ordering code: JL-5N
- 3. Standard IC socket is not recommended. Please use socket "JL-5N".
- 4. When switching inductive load by AC output module without varistor, please connect a varistor as shown in drawing below.
- 5. AC input module has inside logic IC. Please connect bypass condenser (approx. 0.01µ) at pivotal points between VDD and GND. (Conform to general handling instructions for logic IC.)



RoHS Compliance and Lead Free Relay Information

1. General Information

- Relays produced after the specific date code that is indicated on each data sheet are lead-free
 now. Most of our signal and power relays are lead-free. Please refer to Lead-Free Status Info.
 (http://www.fujitsu.com/us/downloads/MICRO/fcai/relays/lead-free-letter.pdf)
- Lead free solder paste currently used in relays is Sn-3.0Ag-0.5Cu.
- All signal and most power relays also comply with RoHS. Please refer to individual data sheets. Relays that are RoHS compliant do not contain the 5 hazardous materials that are restricted by RoHS directive (lead, mercury, chromium IV, PBB, PBDE).
- It has been verified that using lead-free relays in leaded assembly process will not cause any problems (compatible).
- "LF" is marked on each outer and inner carton. (No marking on individual relays).
- To avoid leaded relays (for lead-free sample, etc.) please consult with area sales office.
- We will ship leaded relays as long as the leaded relay inventory exists.

Note: Cadmium was exempted from RoHS on October 21, 2005. (Amendment to Directive 2002/95/EC)

2. Recommended Lead Free Solder Profile

• Recommended solder paste Sn-3.0Ag-0.5Cu.

Reflow Solder condtion

Flow Solder condtion:

Pre-heating: maximum 120°C dip within 5 sec. at 260°C soler bath

Solder by Soldering Iron:

Soldering Iron

Temperature: maximum 360°C Duration: maximum 3 sec.

We highly recommend that you confirm your actual solder conditions

3. Moisture Sensitivity

Moisture Sensitivity Level standard is not applicable to electromechanical realys.

4. Tin Whisker

 Dipped SnAgCu solder is known as low risk tin whisker. No considerable length whisker was found by our in house test.

Fujitsu Components International Headquarter Offices

Japan

Fujitsu Component Limited Gotanda-Chuo Building

3-5, Higashigotanda 2-chome, Shinagawa-ku

Tokyo 141 8630, Japan Tel: (81-3) 5449-7010 Fax: (81-3) 5449-2626

Email: promothq@fcl.fujitsu.com Web: www.fcl.fujitsu.com

North and South America

Fujitsu Components America, Inc. 250 E. Caribbean Drive Sunnyvale, CA 94089 U.S.A. Tel: (1-408) 745-4900

Fax: (1-408) 745-4970

Email: components@us.fujitsu.com

Web: http://www.fujitsu.com/us/services/edevices/components/

Europe

Fujitsu Components Europe B.V.

Diamantlaan 25 2132 WV Hoofddorp Netherlands Tel: (31-23) 5560910 Fax: (31-23) 5560950 Email: info@fceu.fujitsu.com Web: emea.fujitsu.com/components/

Asia Pacific

Fujitsu Components Asia Ltd. 102E Pasir Panjang Road #01-01 Citilink Warehouse Complex

Singapore 118529 Tel: (65) 6375-8560 Fax: (65) 6273-3021 Email: fcal@fcal.fujitsu.com

Web: http://www.fujitsu.com/sg/services/micro/components/

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